L Number		Search Text	DB	Time stamp
1	2328		USPAT;	2004/08/26 15:00
		(layer or film)	US-PGPUB;	
1	1		EPO; JPO;	
			DERWENT; IBM TDB	
8	14	(wafer and (adhesi\$4 and barrier) adj	USPAT;	2004/08/26 15:00
		(layer or film)) and photo near	US-PGPUB;	2004/00/20 15:00
]		(lithograph\$6 and resist) and etch\$4	EPO; JPO;	
	ļ	, , , ,	DERWENT;	
			IBM TDB	
9	11	((wafer and (adhesi\$4 and barrier) adj	USPAT;	2004/08/26 14:59
		(layer or film)) and photo near	US-PGPUB;	
		(lithograph\$6 and resist) and etch\$4) and	EPO; JPO;	
		solder	DERWENT;	
10	1	("20020064935").PN.	IBM_TDB	0001/00/05 51 55
•	_	(20020004935").PN.	USPAT;	2004/08/26 14:58
11	1	("20030099767").PN.	US-PGPUB	2004/00/25 14 50
	_	(20030033707).FN.	USPAT; US-PGPUB	2004/08/26 14:59
12	32288	solder near (bump or ball or sphere or	USPAT:	2004/08/26 14:59
		block or preform)	US-PGPUB;	2004/08/28 14:59
i		1	EPO; JPO;	
			DERWENT;	
			IBM TDB	
13	1228	(solder near (bump or ball or sphere or	USPAT;	2004/08/26 15:00
		block or preform)) and (solder or bump or	US-PGPUB;	
		ball or sphere or block or preform) near	EPO; JPO;	
		(column or stack\$4 or tower)	DERWENT;	
14	288	((solder near (bump or ball or sphere or	IBM_TDB	2224/22/24
	200	block or preform)) and (solder or bump or	USPAT; US-PGPUB;	2004/08/26 15:00
		ball or sphere or block or preform) near	EPO; JPO;	
		(column or stack\$4 or tower)) and (solder	DERWENT;	
		or bump or ball or sphere or block or	IBM TDB	
		preform) near (stack\$4)		
15	14	(((solder near (bump or ball or sphere or	USPAT;	2004/08/26 15:01
		block or preform)) and (solder or bump or	US-PGPUB;	
		ball or sphere or block or preform) near	EPO; JPO;	
		(column or stack\$4 or tower)) and (solder	DERWENT;	
		or bump or ball or sphere or block or	IBM_TDB	
	Ī	<pre>preform) near (stack\$4)) and wafer and (adhesi\$4 and barrier) adj (layer or film)</pre>		
16	o	((((solder near (bump or ball or sphere	USPAT;	2004/00/20 45 55
i		or block or preform)) and (solder or bump	US-PGPUB;	2004/08/26 15:01
		or ball or sphere or block or preform)	EPO; JPO;	
		near (column or stack\$4 or tower)) and	DERWENT;	
1		(solder or bump or ball or sphere or block	IBM TDB	
1		or preform) near (stack\$4)) and wafer and	_	
		(adhesi\$4 and barrier) adj (layer or film)		
17	20) and photo near (lithograph\$6 and resist)		
1'	30	((solder near (bump or ball or sphere or	USPAT;	2004/08/26 15:01
!	J	block or preform)) and (solder or bump or ball or sphere or block or preform) near	US-PGPUB;	
İ	İ	(column or stack\$4 or tower)) and wafer	EPO; JPO;	
ļ	ļ	and (adhesi\$4 and barrier) adj (layer or	DERWENT;	
		film)	IBM_TDB	
18	0	(((solder near (bump or ball or sphere or	USPAT;	2004/08/26 15:01
		block or preform)) and (solder or bump or	US-PGPUB;	2001,00,20 15.01
}		ball or sphere or block or preform) near	EPO; JPO;	
		(column or stack\$4 or tower)) and wafer	DERWENT;	
		and (adhesi\$4 and barrier) adj (layer or	IBM_TDB	
		film)) and photo near (lithograph\$6 and	l	
		resist)		